EVM
h208_MS_TMF8829
h208_MS_TMF8829 PCB
[No Variations]

am OSRAM

EVM

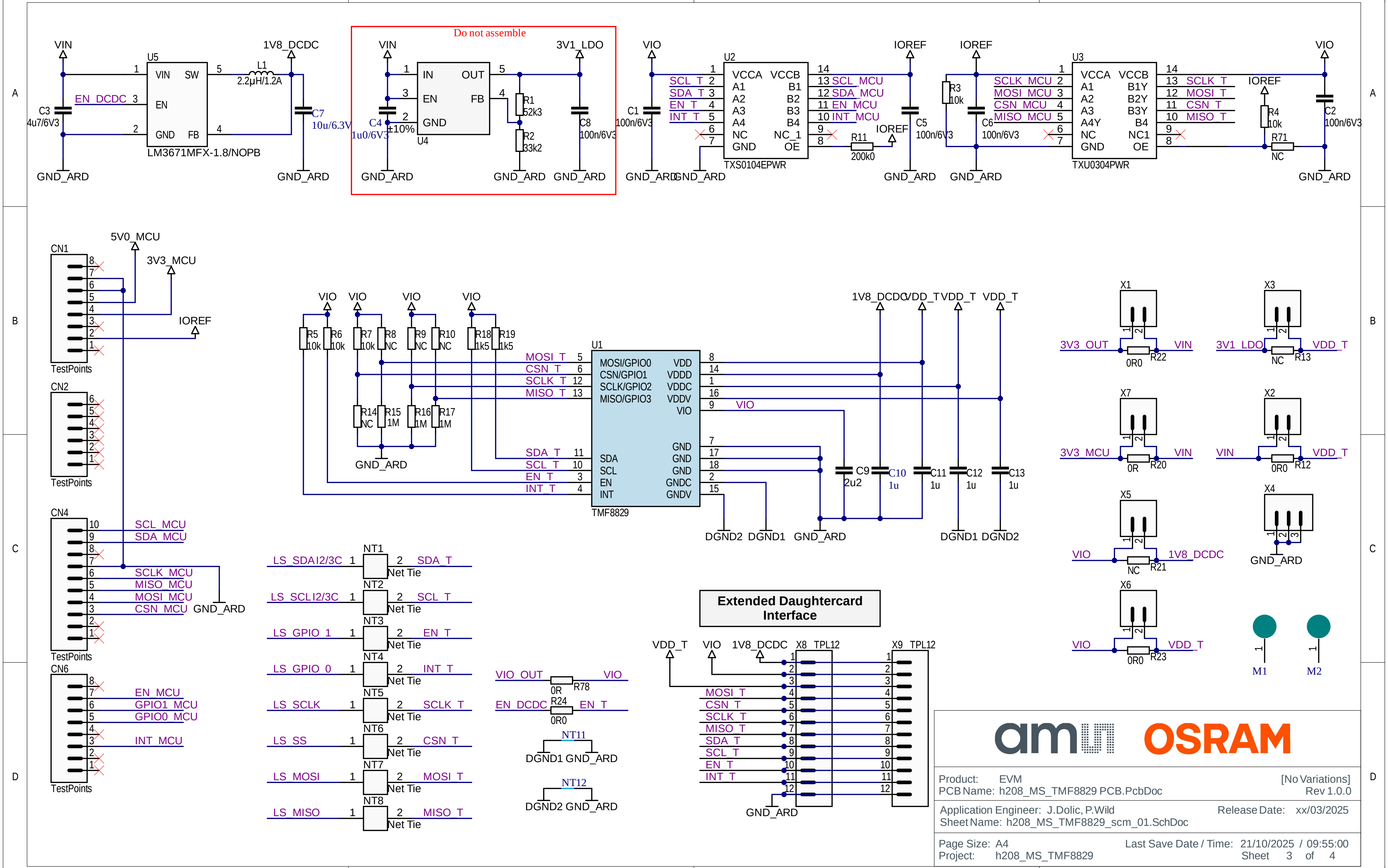
h208_MS_TMF8829 PCB

Table of Contents

Revision History

Rev 1.0.0: Initial Release	Release Date: XX/03/2025

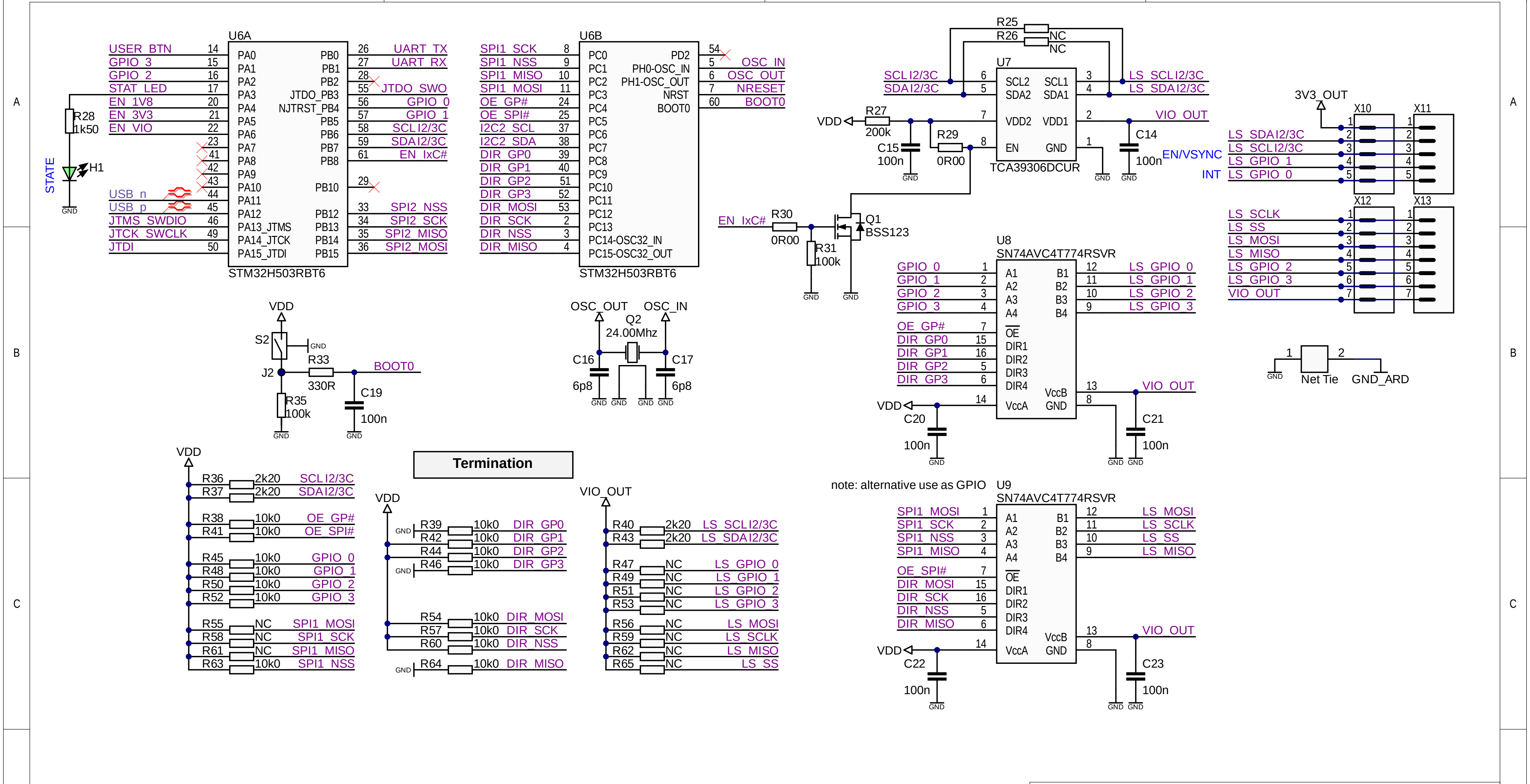
Design Changes



Product: EVM [No Variations]
PCB Name: h208_MS_TMF8829 PCB.PcbDoc Rev 1.0.0

Application Engineer: J.Dolic, P.Wild Release Date: xx/03/2025
Sheet Name: h208_MS_TMF8829_scm_01.SchDoc

Page Size: A4 Last Save Date / Time: 21/10/2025 / 09:55:00
Project: h208_MS_TMF8829 Sheet 3 of 4



Product: EVM [No Variations]
PCB Name: h208_MS_TMF8829 PCB.PcbDoc Rev 1.0.0

Application Engineer: J.Dolic, P.Wild Release Date: xx/03/2025
Sheet Name: h208_MS_TMF8829scm_02.SchDoc

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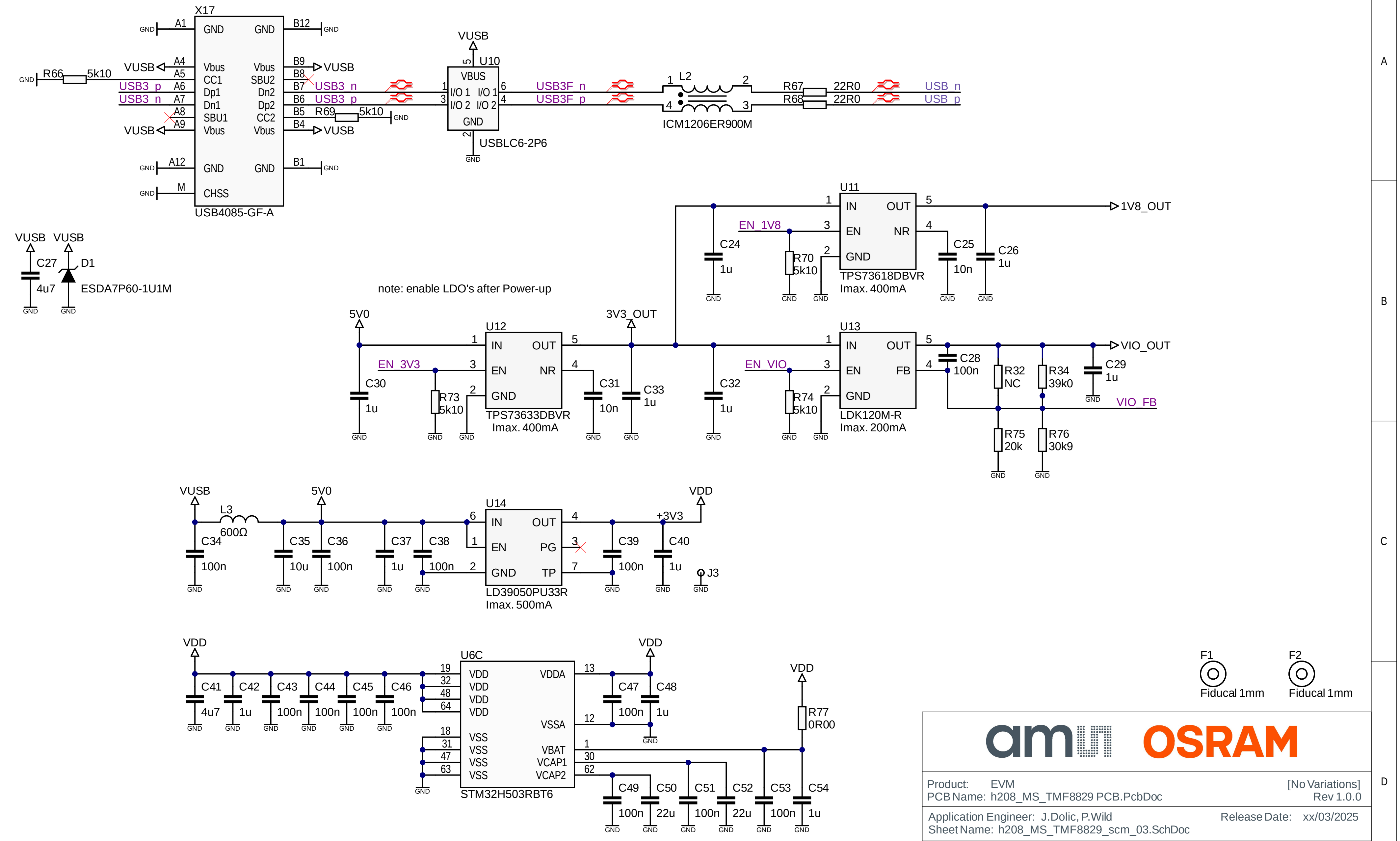
Project: h208_MS_TMF8829 Sheet 4 of 4



ams OSRAM

Product: EVM [No Variations]
PCB Name: h208_MS_TMF8829 PCB.PcbDoc Rev 1.0.0

Application Engineer: J.Dolic, P.Wild Release Date: xx/03/2025
Sheet Name: h208_MS_TMF8829_scm_03.SchDoc

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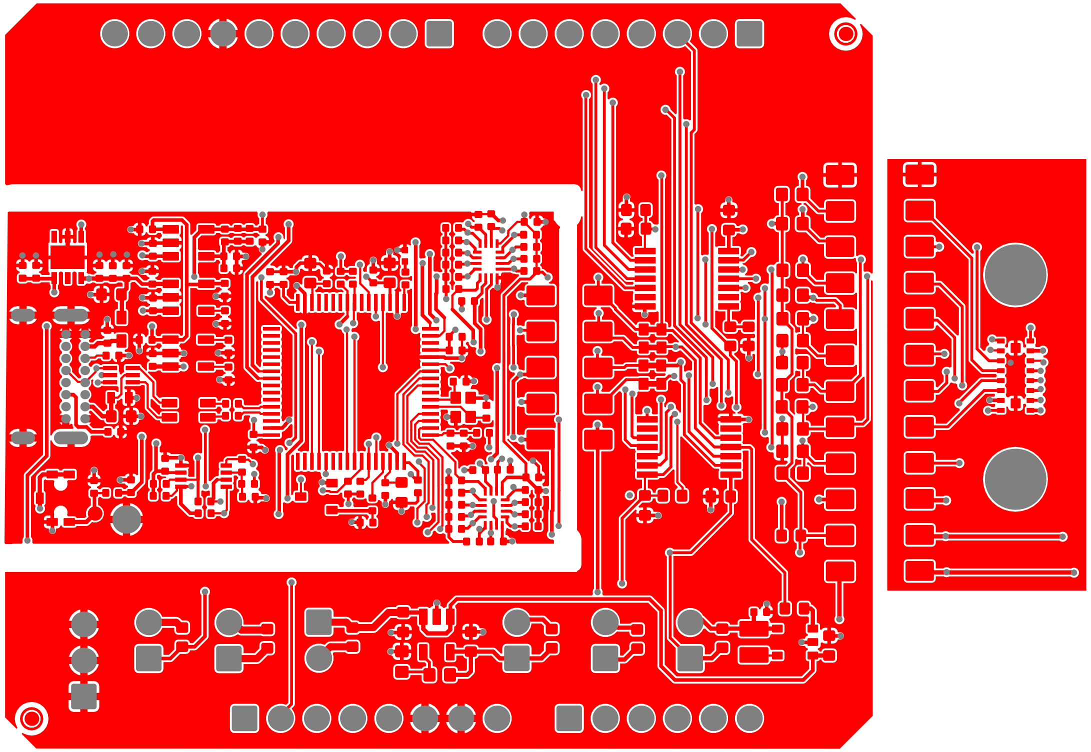
Project: h208_MS_TMF8829 Sheet 5 of 4



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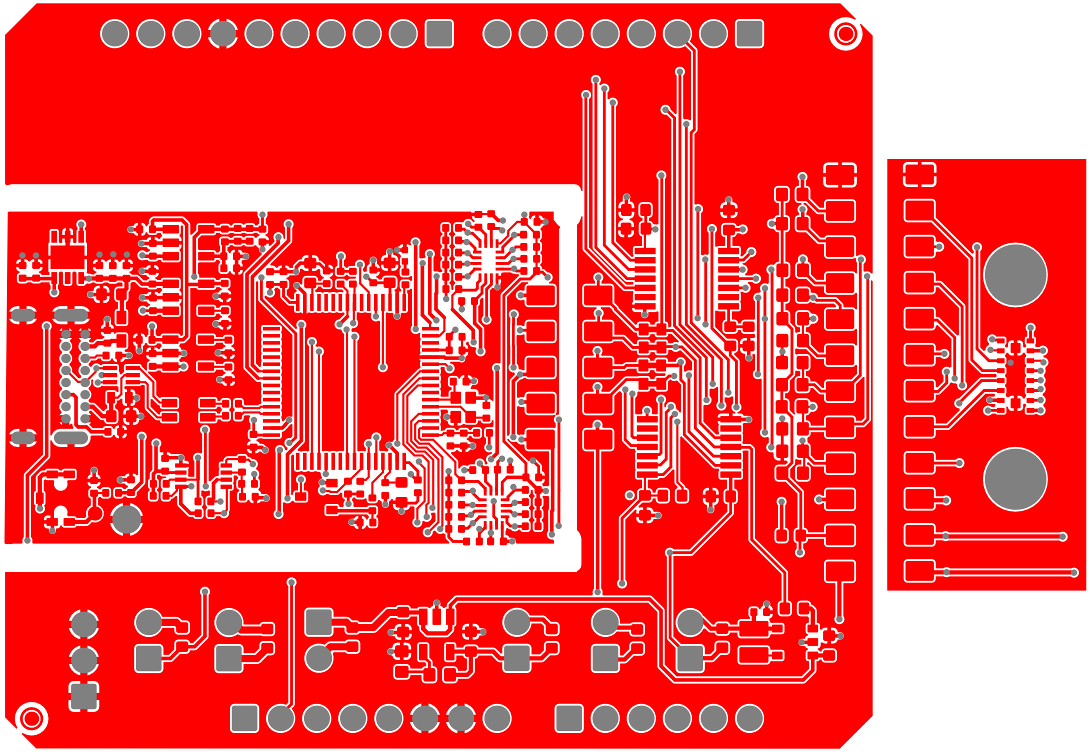

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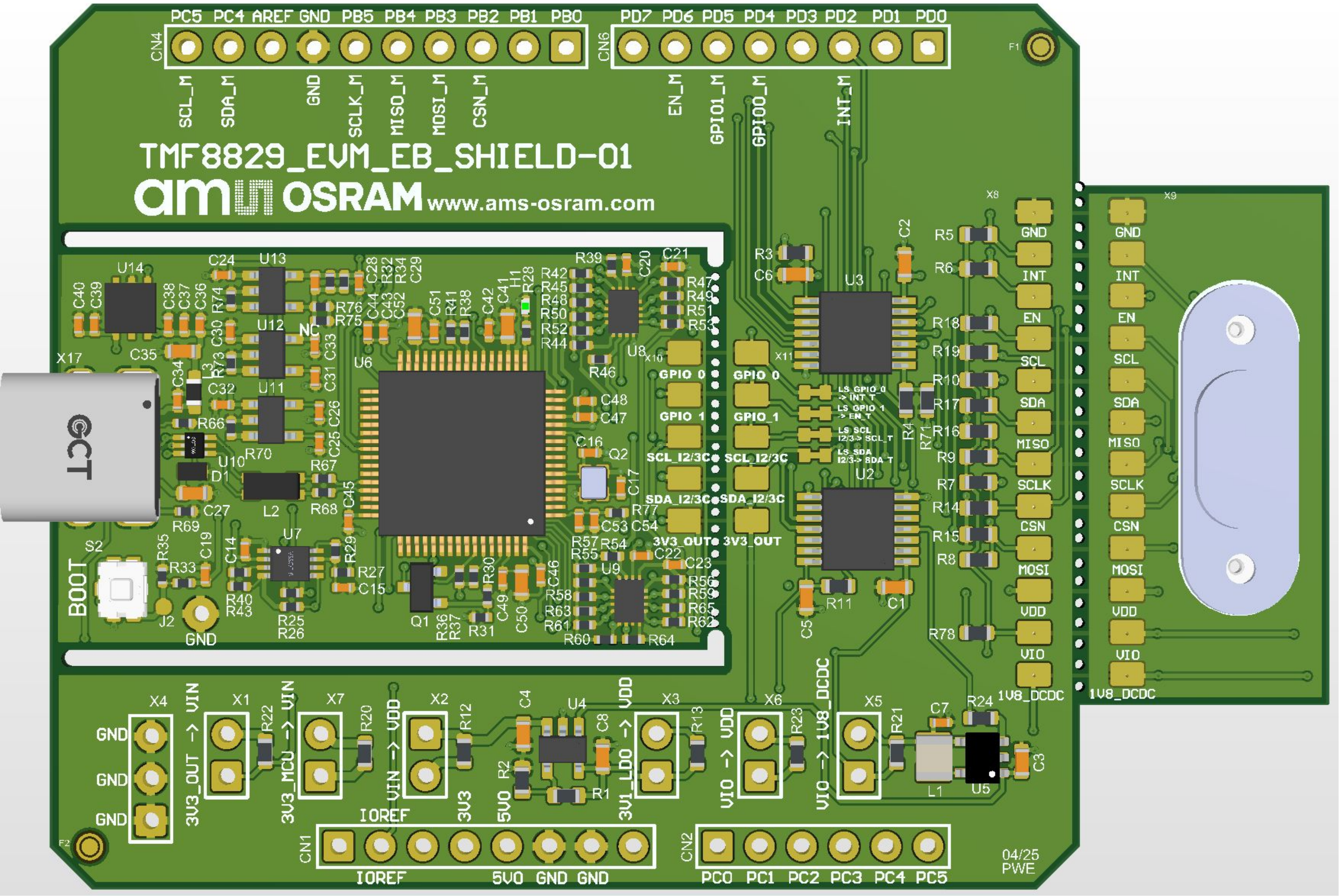
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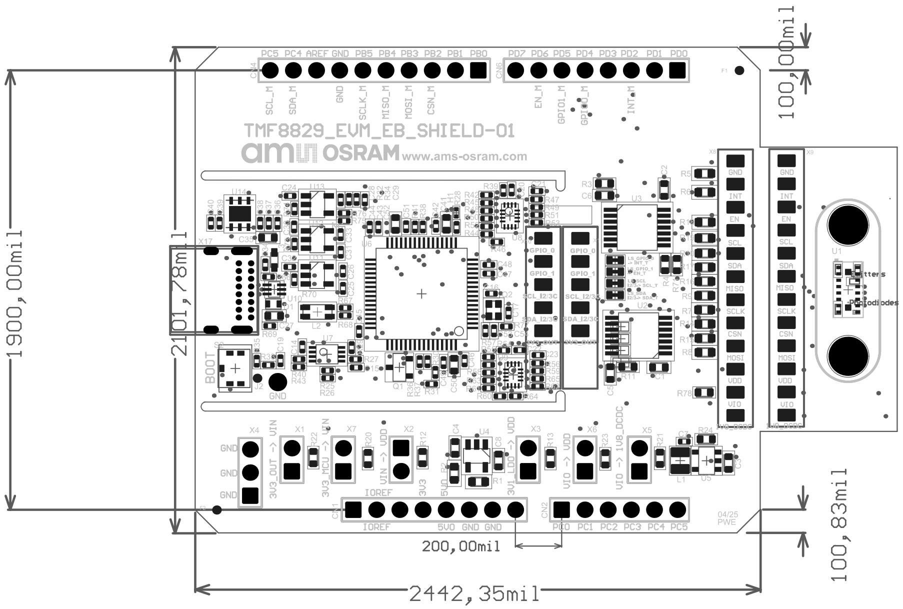
CN4
PD7 PD6 PD5 PD4 PD3 PD2 PD1 PD0
CN6
F1
SCL_M
SDA_M
GND
SCLK_M
MISO_M
MOSI_M
CSN_M
EN_M
GPIO1_M
GPIO0_M
INT_M
TMF8829_EVM_EB_SHIELD-01
ams OSRAM www.ams-osram.com
X8
X9
GND
INT
EN
SCL
SDA
MISO
SCLK
CSN
MOSI
VDD
VIO
1V8_DCDC
U3
U2
U6
U7
U8
U9
U10
U11
U12
U13
U14
X10
X11
GPIO 0
GPIO 1
GPIO_1
SCL_I2/3C
SDA_I2/3C
3V3_OUT
LS_GPIO_0 -> INT_T
LS_GPIO_1 -> EN_T
LS_SCL I2/3-> SCL_T
LS_SDA I2/3-> SDA_T
NC
X17
CCT
BOOT
S2
J2
GND
Q1
Q2
L2
D1
H1
X4
X1
X7
X2
X3
X6
X5
GND
GND
GND
3V3_OUT -> VIN
3V3_MCU -> VIN
VIN -> VDD
3V3
5V0
3V1_LDO -> VDD
VIO -> VDD
VIO -> 1V8_DCDC
U4
U5
L1
IOREF
CN1
IOREF 5V0 GND GND
CN2
PC0 PC1 PC2 PC3 PC4 PC5
F2
04/25
PWE

Layer	Name	Material	Thickness	Constant	Gerber
	Top Overlay				GTO
	Top Solder	Solder Resist	0,40mil	3.5	GTS
1	TOP		0,70mil		GTL
	Dielectric1	FR-4	8,00mil	4.5	
2	MID1		1,40mil		G1
	Dielectric2	FR-4	41,00mil	4.5	
3	MID2		1,40mil		G2
	Dielectric3	FR-4	8,00mil	4.5	
4	BOTTOM		0,70mil		GBL
	Bottom Solder	Solder Resist	0,40mil	3.5	GBS
	Bottom Overlay				GBO

Total board thickness: 62,00mil

Board Details

1. Board Size: '.PCB_X' x '.PCB_Y'
2. Board Thickness: '.PCB_Z'
3. Board Material: '.PCB_Material'
4. Board Finish: '.PCB_Finish'
5. Component count: 187
6. Pad Count: 1188
7. Hole Count: 936
8. Soldermask Color: '.PCB_SolderMaskColor'
9. Silkscreen Color: '.PCB_Silkscreen_Color'
10. No Silkscreen over exposed copper.
11. Dimensions shown are in mils unless marked.
12. No additional silkscreen to be added.
13. Boards Shall be fabricated to IPC-600 Class 1
14. The PCB assembly shall be ROHS compliant.



Layers Currently On

Dimensions	**Board Outline**
Title_Block	**Layer Stack**
Multi-Layer	
Top Courtyard	**Bottom Courtyard**
Top Designator	**Bottom Designator**
Top Overlay	
Top 3D Body	**Bottom 3D Body**

Title .ProjectTitle

Number .ProjectBoardNumber
Rev .ProjectRev

Print Name
TOPAssembly Drawing

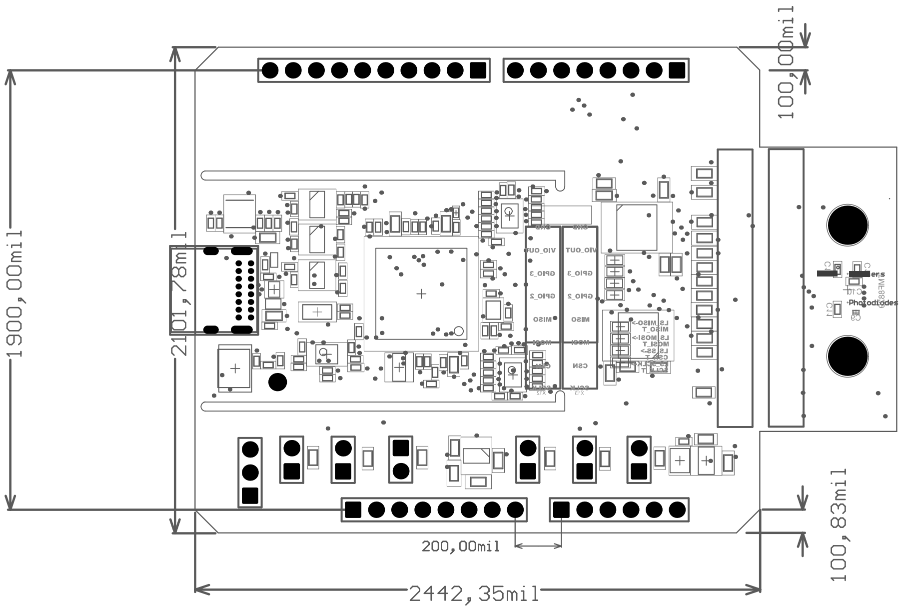
Variant: [No Variations]
Print Date: 21/10/2025
Drawn By:.ProjectEng

Layer	Name	Material	Thickness	Constant	Gerber
	Top Overlay				GTO
	Top Solder	Solder Resist	0,40mil	3.5	GTS
1	TOP		0,70mil		GTL
	Dielectric1	FR-4	8,00mil	4.5	
2	MID1		1,40mil		G1
	Dielectric2	FR-4	41,00mil	4.5	
3	MID2		1,40mil		G2
	Dielectric3	FR-4	8,00mil	4.5	
4	BOTTOM		0,70mil		GBL
	Bottom Solder	Solder Resist	0,40mil	3.5	GBS
	Bottom Overlay				GBO

Total board thickness: 62,00mil

Board Details

1. Board Size: '.PCB_X' x '.PCB_Y'
2. Board Thickness: '.PCB_Z'
3. Board Material: '.PCB_Material'
4. Board Finish: '.PCB_Finish'
5. Component count: 187
6. Pad Count: 1188
7. Hole Count: 936
8. Soldermask Color: '.PCB_SolderMaskColor'
9. Silkscreen Color: '.PCB_Silkscreen_Color'
10. No Silkscreen over exposed copper.
11. Dimensions shown are in mils unless marked.
12. No additional silkscreen to be added.
13. Boards Shall be fabricated to IPC-600 Class 1
14. The PCB assembly shall be ROHS compliant.



Layers Currently On

Dimensions	**Board Outline**
Title_Block	**Layer Stack**
Multi-Layer	
Top Courtyard	**Bottom Courtyard**
Top Designator	**Bottom Designator**
	Bottom Overlay
Top 3D Body	**Bottom 3D Body**

Title .ProjectTitle
Number .ProjectBoardNumber
Rev .ProjectRev
Print Name
MID1Assembly Drawing
Variant: [No Variations]
Print Date: 21/10/2025
Drawn By:.ProjectEng

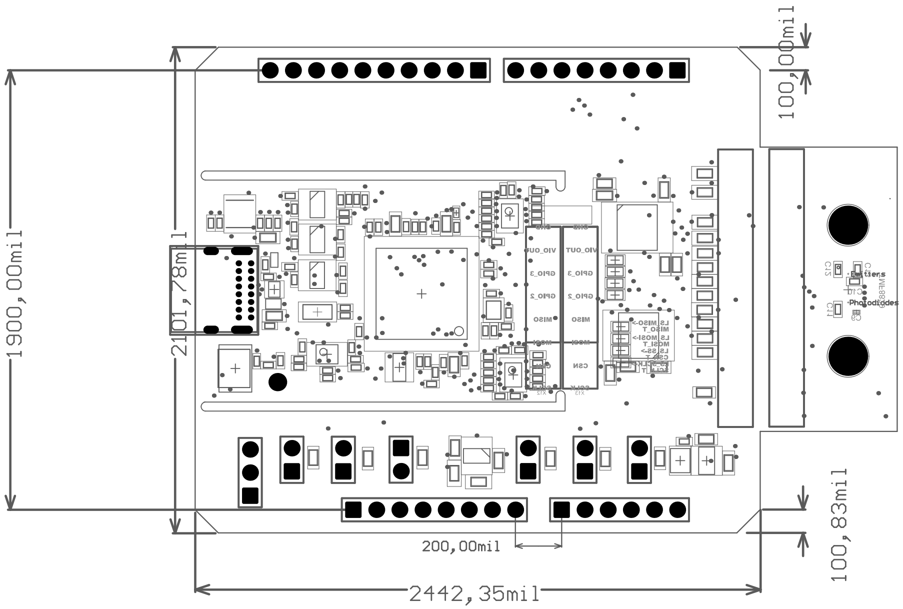
A

Layer	Name	Material	Thickness	Constant	Gerber
	Top Overlay				GTO
	Top Solder	Solder Resist	0,40mil	3.5	GTS
1	TOP		0,70mil		GTL
	Dielectric1	FR-4	8,00mil	4.5	
2	MID1		1,40mil		G1
	Dielectric2	FR-4	41,00mil	4.5	
3	MID2		1,40mil		G2
	Dielectric3	FR-4	8,00mil	4.5	
4	BOTTOM		0,70mil		GBL
	Bottom Solder	Solder Resist	0,40mil	3.5	GBS
	Bottom Overlay				GBO
Total board thickness:			62,00mil		

Board Details

1. Board Size: '.PCB_X' x '.PCB_Y'
2. Board Thickness: '.PCB_Z'
3. Board Material: '.PCB_Material'
4. Board Finish: '.PCB_Finish'
5. Component count: 187
6. Pad Count: 1188
7. Hole Count: 936
8. Soldermask Color: '.PCB_SolderMaskColor'
9. Silkscreen Color: '.PCB_Silkscreen_Color'
10. No Silkscreen over exposed copper.
11. Dimensions shown are in mils unless marked.
12. No additional silkscreen to be added.
13. Boards Shall be fabricated to IPC-600 Class 1
14. The PCB assembly shall be ROHS compliant.

B



C

Layers Currently On

Dimensions	**Board Outline**
Title_Block	**Layer Stack**
Multi-Layer	
Top Courtyard	**Bottom Courtyard**
Top Designator	**Bottom Designator**
	Bottom Overlay
Top 3D Body	**Bottom 3D Body**

D

Title
.ProjectTitle

Number
.ProjectBoardNumber

Rev
.ProjectRev

Print Name
MID2Assembly Drawing

Variant: [No Variations]

Print Date: 21/10/2025

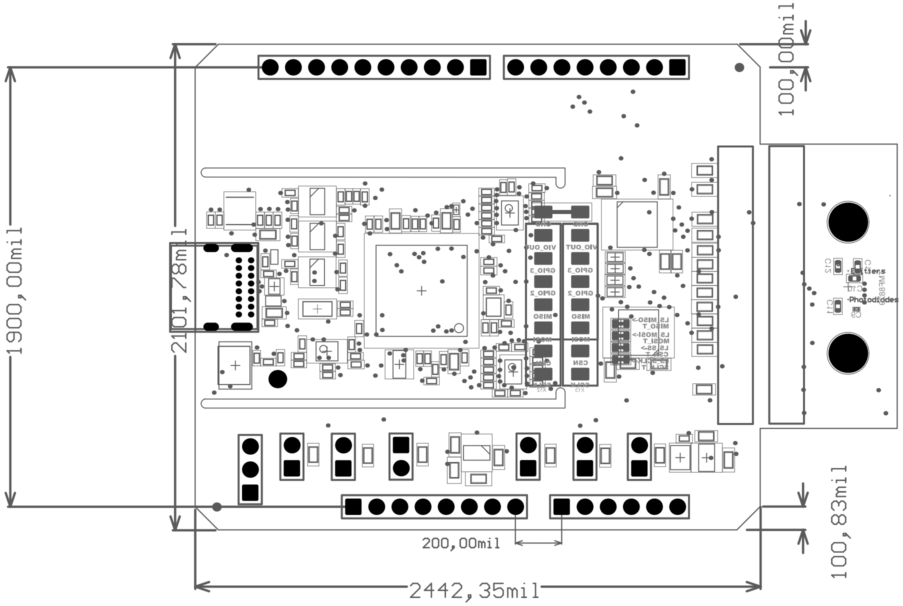
Drawn By:.ProjectEng

Layer	Name	Material	Thickness	Constant	Gerber
	Top Overlay				GTO
	Top Solder	Solder Resist	0,40mil	3.5	GTS
1	TOP		0,70mil		GTL
	Dielectric1	FR-4	8,00mil	4.5	
2	MID1		1,40mil		G1
	Dielectric2	FR-4	41,00mil	4.5	
3	MID2		1,40mil		G2
	Dielectric3	FR-4	8,00mil	4.5	
4	BOTTOM		0,70mil		GBL
	Bottom Solder	Solder Resist	0,40mil	3.5	GBS
	Bottom Overlay				GBO

Total board thickness: 62,00mil

Board Details

1. Board Size: '.PCB_X' x '.PCB_Y'
2. Board Thickness: '.PCB_Z'
3. Board Material: '.PCB_Material'
4. Board Finish: '.PCB_Finish'
5. Component count: 187
6. Pad Count: 1188
7. Hole Count: 936
8. Soldermask Color: '.PCB_SolderMaskColor'
9. Silkscreen Color: '.PCB_Silkscreen_Color'
10. No Silkscreen over exposed copper.
11. Dimensions shown are in mils unless marked.
12. No additional silkscreen to be added.
13. Boards Shall be fabricated to IPC-600 Class 1
14. The PCB assembly shall be ROHS compliant.



Layers Currently On

Dimensions	**Board Outline**
Title_Block	**Layer Stack**
Multi-Layer	
Top Courtyard	**Bottom Courtyard**
Top Designator	**Bottom Designator**
	Bottom Overlay
Top 3D Body	**Bottom 3D Body**

Title .ProjectTitle

Number .ProjectBoardNumber

Rev .ProjectRev

Print Name
BOTTOMAssembly Drawing

Variant: [No Variations]

Print Date: 21/10/2025

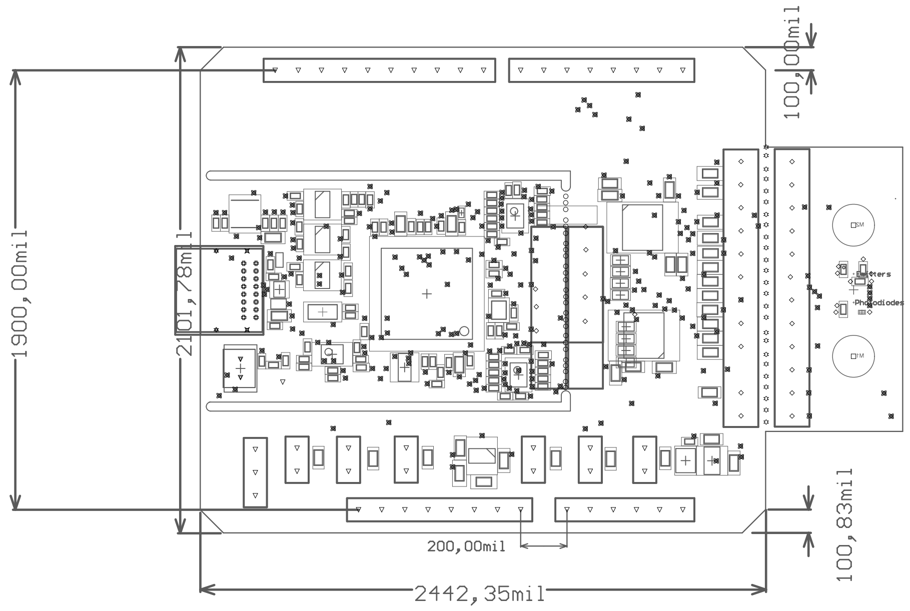
Drawn By:.ProjectEng

Layer	Name	Material	Thickness	Constant	Gerber
	Top Overlay				GTO
	Top Solder	Solder Resist	0,40mil	3.5	GTS
1	TOP		0,70mil		GTL
	Dielectric1	FR-4	8,00mil	4.5	
2	MID1		1,40mil		G1
	Dielectric2	FR-4	41,00mil	4.5	
3	MID2		1,40mil		G2
	Dielectric3	FR-4	8,00mil	4.5	
4	BOTTOM		0,70mil		GBL
	Bottom Solder	Solder Resist	0,40mil	3.5	GBS
	Bottom Overlay				GBO

Total board thickness: 62,00mil

Board Details

1. Board Size: '.PCB_X' x '.PCB_Y'
2. Board Thickness: '.PCB_Z'
3. Board Material: '.PCB_Material'
4. Board Finish: '.PCB_Finish'
5. Component count: 187
6. Pad Count: 1188
7. Hole Count: 936
8. Soldermask Color: '.PCB_SolderMaskColor'
9. Silkscreen Color: '.PCB_Silkscreen_Color'
10. No Silkscreen over exposed copper.
11. Dimensions shown are in mils unless marked.
12. No additional silkscreen to be added.
13. Boards Shall be fabricated to IPC-600 Class 1
14. The PCB assembly shall be ROHS compliant.



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape
✡	2	0,600mm (23,62mil)	PTH	Slot	TOP - BOTTOM	Pad	Rounded Rectangle
⌘	2	0,600mm (23,62mil)	PTH	Slot	TOP - BOTTOM	Pad	Rounded Rectangle
∇	2	0,700mm (27,56mil)	NPTH	Round	TOP - BOTTOM	Pad	Rounded
□	2	2,600mm (102,36mil)	PTH	Round	TOP - BOTTOM	Pad	Rounded
⊕	16	0,400mm (15,75mil)	PTH	Round	TOP - BOTTOM	Pad	Rounded
✡	25	0,600mm (23,62mil)	NPTH	Round	TOP - BOTTOM	Pad	Rounded
○	26	0,500mm (19,69mil)	NPTH	Round	TOP - BOTTOM	Pad	Rounded
◇	40	0,200mm (7,87mil)	PTH	Round	TOP - BOTTOM	Via	Rounded
▽	48	1,000mm (39,37mil)	PTH	Round	TOP - BOTTOM	Pad	(Mixed)
⌘	259	0,200mm (7,87mil)	PTH	Round	TOP - BOTTOM	Via	Rounded
	422 Total						

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

Layers Currently On

Dimensions **Title_Block** **Drill Drawing**	**Board Outline** **Layer Stack**
Top Courtyard **Top Designator**	**Bottom Courtyard** **Bottom Designator**
Top 3D Body	**Bottom 3D Body**

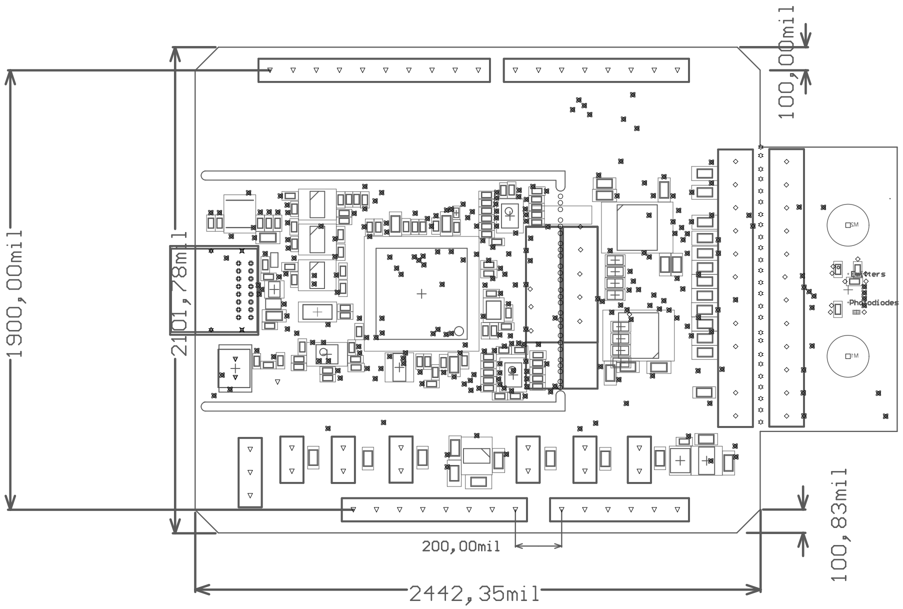
Title .ProjectTitle
Number .ProjectBoardNumber
Rev .ProjectRev
Print Name
Drill Drawing For (TOP - BOTTOM)
Variant: [No Variations]
Print Date: 21/10/2025
Drawn By:.ProjectEng

Layer	Name	Material	Thickness	Constant	Gerber
	Top Overlay				GTO
	Top Solder	Solder Resist	0,40mil	3.5	GTS
1	TOP		0,70mil		GTL
	Dielectric1	FR-4	8,00mil	4.5	
2	MID1		1,40mil		G1
	Dielectric2	FR-4	41,00mil	4.5	
3	MID2		1,40mil		G2
	Dielectric3	FR-4	8,00mil	4.5	
4	BOTTOM		0,70mil		GBL
	Bottom Solder	Solder Resist	0,40mil	3.5	GBS
	Bottom Overlay				GBO

Total board thickness: 62,00mil

Board Details

1. Board Size: '.PCB_X' x '.PCB_Y'
2. Board Thickness: '.PCB_Z'
3. Board Material: '.PCB_Material'
4. Board Finish: '.PCB_Finish'
5. Component count: 187
6. Pad Count: 1188
7. Hole Count: 936
8. Soldermask Color: '.PCB_SolderMaskColor'
9. Silkscreen Color: '.PCB_Silkscreen_Color'
10. No Silkscreen over exposed copper.
11. Dimensions shown are in mils unless marked.
12. No additional silkscreen to be added.
13. Boards Shall be fabricated to IPC-600 Class 1
14. The PCB assembly shall be ROHS compliant.



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape
✡	2	0,600mm (23,62mil)	PTH	Slot	TOP - BOTTOM	Pad	Rounded Rectangle
⌘	2	0,600mm (23,62mil)	PTH	Slot	TOP - BOTTOM	Pad	Rounded Rectangle
∇	2	0,700mm (27,56mil)	NPTH	Round	TOP - BOTTOM	Pad	Rounded
□	2	2,600mm (102,36mil)	PTH	Round	TOP - BOTTOM	Pad	Rounded
⊞	16	0,400mm (15,75mil)	PTH	Round	TOP - BOTTOM	Pad	Rounded
✡	25	0,600mm (23,62mil)	NPTH	Round	TOP - BOTTOM	Pad	Rounded
○	26	0,500mm (19,69mil)	NPTH	Round	TOP - BOTTOM	Pad	Rounded
◇	40	0,200mm (7,87mil)	PTH	Round	TOP - BOTTOM	Via	Rounded
▽	48	1,000mm (39,37mil)	PTH	Round	TOP - BOTTOM	Pad	(Mixed)
⌧	259	0,200mm (7,87mil)	PTH	Round	TOP - BOTTOM	Via	Rounded
	422 Total						

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

Layers Currently On

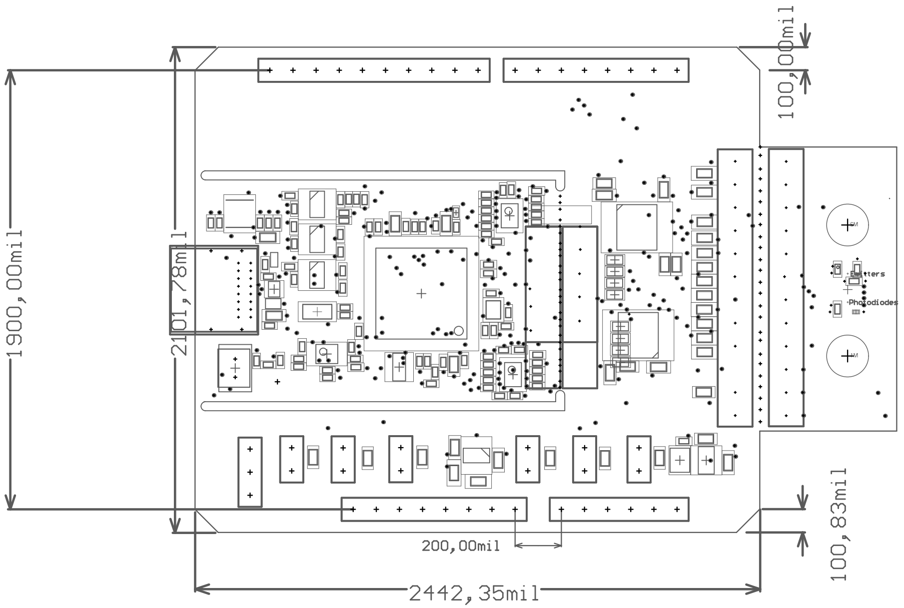
Dimensions	**Board Outline**
Title_Block	**Layer Stack**
Drill Drawing	
Top Courtyard	**Bottom Courtyard**
Top Designator	**Bottom Designator**
Top 3D Body	**Bottom 3D Body**

Title .ProjectTitle
Number .ProjectBoardNumber
Rev .ProjectRev
Print Name
Drill Drawing For (TOP - MID1)
Variant: [No Variations]
Print Date: 21/10/2025
Drawn By:.ProjectEng

Layer	Name	Material	Thickness	Constant	Gerber
	Top Overlay				GTO
	Top Solder	Solder Resist	0,40mil	3.5	GTS
1	TOP		0,70mil		GTL
	Dielectric1	FR-4	8,00mil	4.5	
2	MID1		1,40mil		G1
	Dielectric2	FR-4	41,00mil	4.5	
3	MID2		1,40mil		G2
	Dielectric3	FR-4	8,00mil	4.5	
4	BOTTOM		0,70mil		GBL
	Bottom Solder	Solder Resist	0,40mil	3.5	GBS
	Bottom Overlay				GBO
Total board thickness:			62,00mil		

Board Details

1. Board Size: '.PCB_X' x '.PCB_Y'
2. Board Thickness: '.PCB_Z'
3. Board Material: '.PCB_Material'
4. Board Finish: '.PCB_Finish'
5. Component count: 187
6. Pad Count: 1188
7. Hole Count: 936
8. Soldermask Color: '.PCB_SolderMaskColor'
9. Silkscreen Color: '.PCB_Silkscreen_Color'
10. No Silkscreen over exposed copper.
11. Dimensions shown are in mils unless marked.
12. No additional silkscreen to be added.
13. Boards Shall be fabricated to IPC-600 Class 1
14. The PCB assembly shall be ROHS compliant.



Layers Currently On

Dimensions	**Board Outline**
Title_Block	**Layer Stack**
	Drill Guide
Top Courtyard	**Bottom Courtyard**
Top Designator	**Bottom Designator**
Top 3D Body	**Bottom 3D Body**

Title .ProjectTitle

Number .ProjectBoardNumber
Rev .ProjectRev

Print Name
Drill Guide For (TOP - BOTTOM)

Variant: [No Variations]
Print Date: 21/10/2025
Drawn By:.ProjectEng

Layer	Name	Material	Thickness	Constant	Gerber
	Top Overlay				GTO
	Top Solder	Solder Resist	0,40mil	3.5	GTS
1	TOP		0,70mil		GTL
	Dielectric1	FR-4	8,00mil	4.5	
2	MID1		1,40mil		G1
	Dielectric2	FR-4	41,00mil	4.5	
3	MID2		1,40mil		G2
	Dielectric3	FR-4	8,00mil	4.5	
4	BOTTOM		0,70mil		GBL
	Bottom Solder	Solder Resist	0,40mil	3.5	GBS
	Bottom Overlay				GBO

Total board thickness: 62,00mil

Board Details

1. Board Size: '.PCB_X' x '.PCB_Y'
2. Board Thickness: '.PCB_Z'
3. Board Material: '.PCB_Material'
4. Board Finish: '.PCB_Finish'
5. Component count: 187
6. Pad Count: 1188
7. Hole Count: 936
8. Soldermask Color: '.PCB_SolderMaskColor'
9. Silkscreen Color: '.PCB_Silkscreen_Color'
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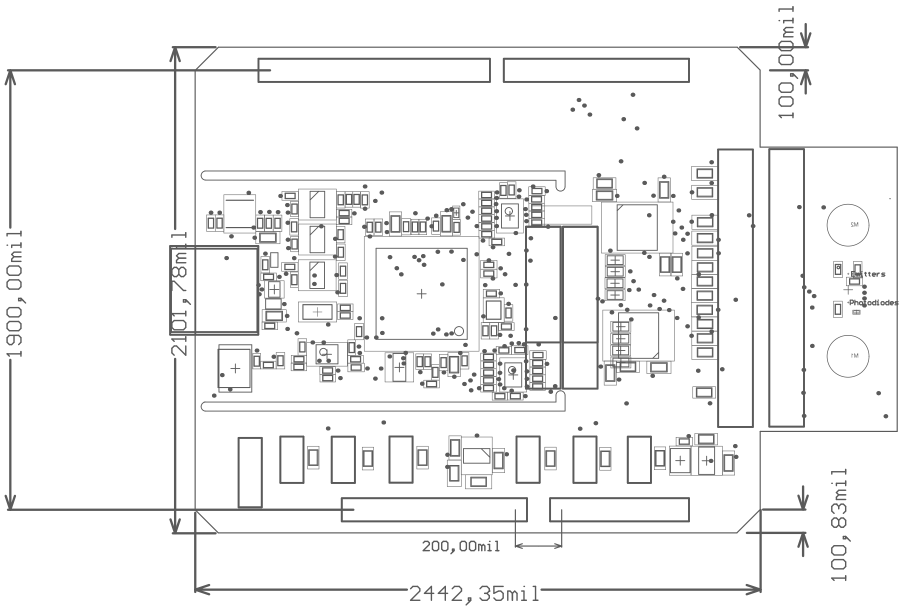
12. No additional silkscreen to be added.
13. Boards Shall be fabricated to IPC-600 Class 1
14. The PCB assembly shall be ROHS compliant.



Layers Currently On

Dimensions Title_Block	Board Outline Layer Stack **Drill Guide**
Top Courtyard Top Designator	Bottom Courtyard Bottom Designator
Top 3D Body	Bottom 3D Body

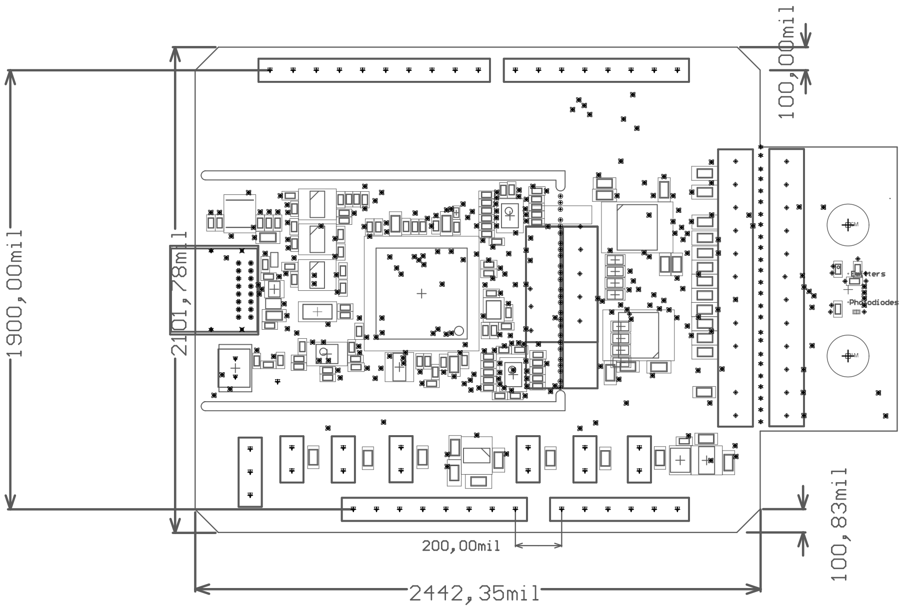
Title .ProjectTitle
Number .ProjectBoardNumber
Rev .ProjectRev
Print Name
Drill Guide For (TOP - MID1)
Variant: [No Variations]
Print Date: 21/10/2025
Drawn By:.ProjectEng

Layer	Name	Material	Thickness	Constant	Gerber
	Top Overlay				GTO
	Top Solder	Solder Resist	0,40mil	3.5	GTS
1	TOP		0,70mil		GTL
	Dielectric1	FR-4	8,00mil	4.5	
2	MID1		1,40mil		G1
	Dielectric2	FR-4	41,00mil	4.5	
3	MID2		1,40mil		G2
	Dielectric3	FR-4	8,00mil	4.5	
4	BOTTOM		0,70mil		GBL
	Bottom Solder	Solder Resist	0,40mil	3.5	GBS
	Bottom Overlay				GBO

Total board thickness: 62,00mil

Board Details

1. Board Size: '.PCB_X' x '.PCB_Y'
2. Board Thickness: '.PCB_Z'
3. Board Material: '.PCB_Material'
4. Board Finish: '.PCB_Finish'
5. Component count: 187
6. Pad Count: 1188
7. Hole Count: 936
8. Soldermask Color: '.PCB_SolderMaskColor'
9. Silkscreen Color: '.PCB_Silkscreen_Color'
10. No Silkscreen over exposed copper.
11. Dimensions shown are in mils unless marked.
12. No additional silkscreen to be added.
13. Boards Shall be fabricated to IPC-600 Class 1
14. The PCB assembly shall be ROHS compliant.



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape
✵	2	0,600mm (23,62mil)	PTH	Slot	TOP - BOTTOM	Pad	Rounded Rectangle
⌘	2	0,600mm (23,62mil)	PTH	Slot	TOP - BOTTOM	Pad	Rounded Rectangle
⊽	2	0,700mm (27,56mil)	NPTH	Round	TOP - BOTTOM	Pad	Rounded
□	2	2,600mm (102,36mil)	PTH	Round	TOP - BOTTOM	Pad	Rounded
⊞	16	0,400mm (15,75mil)	PTH	Round	TOP - BOTTOM	Pad	Rounded
✡	25	0,600mm (23,62mil)	NPTH	Round	TOP - BOTTOM	Pad	Rounded
○	26	0,500mm (19,69mil)	NPTH	Round	TOP - BOTTOM	Pad	Rounded
◇	40	0,200mm (7,87mil)	PTH	Round	TOP - BOTTOM	Via	Rounded
▽	48	1,000mm (39,37mil)	PTH	Round	TOP - BOTTOM	Pad	(Mixed)
⌧	259	0,200mm (7,87mil)	PTH	Round	TOP - BOTTOM	Via	Rounded
	422 Total						

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

Layers Currently On

Dimensions	**Board Outline**
Title_Block	**Layer Stack**
Drill Drawing	**Drill Guide**
Top Courtyard	**Bottom Courtyard**
Top Designator	**Bottom Designator**
Top 3D Body	**Bottom 3D Body**

Title .ProjectTitle

Number .ProjectBoardNumber
Rev .ProjectRev

Print Name
Combination Drill Guide For (TOP - BOTTOM)

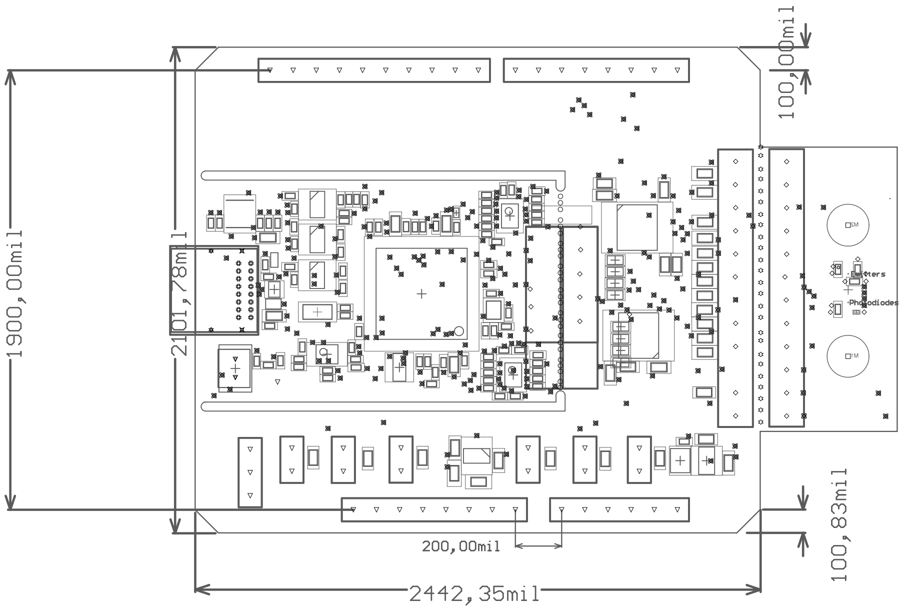
Variant: [No Variations]
Print Date: 21/10/2025
Drawn By:.ProjectEng

Layer	Name	Material	Thickness	Constant	Gerber
	Top Overlay				GTO
	Top Solder	Solder Resist	0,40mil	3.5	GTS
1	TOP		0,70mil		GTL
	Dielectric1	FR-4	8,00mil	4.5	
2	MID1		1,40mil		G1
	Dielectric2	FR-4	41,00mil	4.5	
3	MID2		1,40mil		G2
	Dielectric3	FR-4	8,00mil	4.5	
4	BOTTOM		0,70mil		GBL
	Bottom Solder	Solder Resist	0,40mil	3.5	GBS
	Bottom Overlay				GBO

Total board thickness: 62,00mil

Board Details

1. Board Size: '.PCB_X' x '.PCB_Y'
2. Board Thickness: '.PCB_Z'
3. Board Material: '.PCB_Material'
4. Board Finish: '.PCB_Finish'
5. Component count: 187
6. Pad Count: 1188
7. Hole Count: 936
8. Soldermask Color: '.PCB_SolderMaskColor'
9. Silkscreen Color: '.PCB_Silkscreen_Color'
10. No Silkscreen over exposed copper.
11. Dimensions shown are in mils unless marked.
12. No additional silkscreen to be added.
13. Boards Shall be fabricated to IPC-600 Class 1
14. The PCB assembly shall be ROHS compliant.



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Top Designator	**Bottom Designator**
Top 3D Body	**Bottom 3D Body**

Title .ProjectTitle
Number .ProjectBoardNumber
Rev .ProjectRev
Print Name
Combination Drill Guide For (TOP - MID1)
Variant: [No Variations]
Print Date: 21/10/2025
Drawn By:.ProjectEng

Bill of Materials

None

Company: ams AG
Application Engineer: J.Dolic, P.Wild
Product Number: EVM
ARS Project Name: h208_MS_TMF8829
Boardtype & Version: h208_MS_TMF8829 PCB
Release Date: xx/03/2025
Revision: Rev 1.0.0

remarks: Components with designator R or C are exempted for procurement in the manufacturer. Only design and electronic parameters must be the same or better.

Index	Designator	Description	Manufacturer 1	Manufacturer Part Number 1	Supplier 1	Supplier Part Number 1	Stock Number Jena 1	Quantity
1, 2,	C1, C2, C5, C6	Ceramic Capacitor, Multilayer, Ceramic,	KYOCERA AVX	06036C104JAT2A	Mouser	581-06036C104JAT2A		4
3	C3	4.7µF ±20% 6.3V Ceramic Capacitor	Yageo Group	CC0603MRX5R5BB475	Mouser	603-CC603MRX5R5BB475		1
6	C7	10µF ±20% 6.3V Ceramic Capacitor	Murata	GRM155R60J106ME15D	DigiKey	490-13238-1-ND		1
7	C9	2.2 µF ±20% 6.3V Ceramic Capacitor	Murata	GRM033R60J225ME47D	DigiKey	490-13225-1-ND		1
8	C10	1.0 µF ±10% 6.3V Ceramic Capacitor	KYOCERA AVX	04026D105MAT2A	Mouser	581-04026D105M		1
9, 10,	C11, C12, C13	CAP CER 1UF 6.3V X7R 0402 -	Murata	GRM155R70J105KA12J	Future Electronics	4057312	AMS10714_1005_0402	3
12,	C14, C15, C19, C20, C21,	CAP CER 0.1UF 50V X7R 0402	any		any		4917	20
14,	C16, C17	CAP CER 6.8PF 50V NPO 1005	any		any			2
21,	C24, C26, C29, C30, C32,	CAP CER 1UF 16V X5R 0402	any		any			11
22,	C25, C31	CAP CER 10000PF 50V X7R 0402	any		any		AMS10663_1005_0402	2
24	C27	CAP CER 4.7UF 16V X5R 0603	any		any			1
32	C35	CAP CER 10UF 10V X5R 0603	any		any			1
38	C41	CAP CER 4.7UF 10V X5R 0603	any		any			1
47,	C50, C52	CAP CER 22UF 10V X5R 0603	any		any			2
52	H1	LED green 1mmx0.5mm	Kingbright	KPHHS-1005CGCK	RS Components	861-0122		1
53	L1	1µH Shielded Multilayer Inductor 1.5A	TDK	MLP2520S2R2MT0S1	DigiKey	445-6373-1-ND		1
54	L2	2 Line Common Mode Choke Surface	Vishay	ICM1206ER900M	DigiKey	541-4324-1-ND		1
55	L3	WE-CBF SMD EMI Suppression Ferrite	Wurth Elektronik	742792651	DigiKey	732-1593-1-ND		1
56	M1	Mounting nut M1.6 thread						1
57	M2	Mounting nut M1.6 thread						1
58	Q1	N-Channel 100V 150mA (Ta) 250mW	Nexperia	BSS123,215	DigiKey	1727-4246-1-ND		1
59	Q2	Crystal, 24 MHz	NDK	NX2016SA-24M-EXS00A-CS08891				1
60,	R3, R4	Res Thick Film 0201 200K Ohm 1%	Vishay	CRCW0201200KFNED	Mouser	71-CRCW0201200KFNED		2
62,	R5, R6, R7	RES SMD 10 KOHM 1% 1/16W 0603	Vishay	CRCW060310K0FKEA	Newark	25AC7296		3
65	R11	Res Thick Film 0201 200K Ohm 1%	Vishay	CRCW0201200KFNED	Mouser	71-CRCW0201200KFNED		1
66,	R12, R22, R23, R24	Zero Ohm Resistor, Jumper, 0603 [1608	Vishay	CRCW06030000Z0EI	Mouser	71-CRCW06030000Z0EI		4
67,	R15, R16, R17	RES SMD 1 MOHM 0.1% 1/10W 0603	Yageo Group	RT0603BRD071ML	Mouser	603-RT0603BRD071ML		3
70,	R18, R19	RES SMD 10 KOHM 1% 1/16W 0603	Vishay	CRCW060310K0FKEA	Newark	25AC7296		2
72,	R20, R78	Zero Ohm Resistor, Jumper, 0603 [1608	Vishay	CRCW06030000Z0EI	Mouser	71-CRCW06030000Z0EI		2
76	R27	RES SMD 200k 1% 0.063W 1005	any		any		E002A000908	1
77	R28	RES SMD 1k50 1% 0.063W 1005	any		any		E002A000866	1
78,	R29, R30, R77	RES SMD 0R00 1005	any		any		E002A000692	3
80,	R31, R35	RES SMD 100k 1% 0.063W 1005	any		any		E002A000742	2
81	R33	RES SMD 330R 1% 0.063W 1005	any		any		E002A000814	1
82	R34	RES SMD 39k0 1% 0.063W 1005	any		any		E002A000777	1
84,	R36, R37, R40, R43	RES SMD 2k20 1% 0.063W 1005	any		any		E002A000703	4
86,	R38, R39, R41, R42, R44,	RES SMD 10k0 1% 0.063W 1005	any		any		E002A000690	15
103,	R66, R69, R70, R73, R74	RES SMD 5k10 1% 0.063W 1005	any		any		E002A001084	5
104,	R67, R68	RES SMD 22R0 1% 0.063W 1005	any		any		E002A000699	2
110	R75	RES SMD 20K OHM 0.1% 1/16W 0402	any		any			1
111	R76	RES SMD 30.9KOHM 0.1% 1/16W	any		any			1
114	S2	Tactile Switch SPST-NO Top Actuated	Mitsumi	R-667903	DigiKey	2508-R-667903CT-ND		1
115	U1	Multizone Time-of-Flight Sensor	ams-OSRAM USA INC.	TMF8829				1
116	U2	Integrated Circuit	Texas Instruments	TXS0104EPWR	Mouser	595-TXS0104EPWR		1
117	U3	Integrated Circuit	Texas Instruments	TXU0304PWR	Mouser	TXU0304EPWR		1
118	U5	Buck Switching Regulator IC Positive	Texas Instruments	LM3671MFX-1.8/NOPB	DigiKey	296-41425-1-ND		1
119	U6	ARM® Cortex®-M33 STM32H5	STMicroelectronics	STM32H503RBT6	DigiKey	497-STM32H503RBT6-ND		1
120	U7	Voltage Level Translator Bidirectional 1	Texas Instruments	TCA39306DCUR	DigiKey	296-TCA39306DCURCT-ND		1
121,	U8, U9	Voltage Level Translator Bidirectional 1	Texas Instruments	SN74AVC4T774RSVR	Mouser	595-SN74AVC4T774RSVR		2
123	U10	17V Clamp 5A (8/20µs) Ipp Tvs Diode	STMicroelectronics	USBLC6-2P6	DigiKey	497-5026-1-ND		1
124	U11	Linear Voltage Regulator IC Positive	Texas Instruments	TPS73618DBVR	DigiKey	296-27063-1-ND		1
125	U12	Linear Voltage Regulator IC Positive	Texas Instruments	TPS73633DBVR	DigiKey	296-27064-1-ND		1
126	U13	Linear Voltage Regulator IC Positive	STMicroelectronics	LDK120M-R	DigiKey	497-13501-1-ND		1
127	U14	Linear Voltage Regulator IC Positive	STMicroelectronics	LD39050PU33R	DigiKey	497-8716-1-ND		1
128	X17	USB-C (USB TYPE-C) USB 2.0	Global Connector	USB4085-GF-A	DigiKey	2073-USB4085-GF-ACT-ND		1